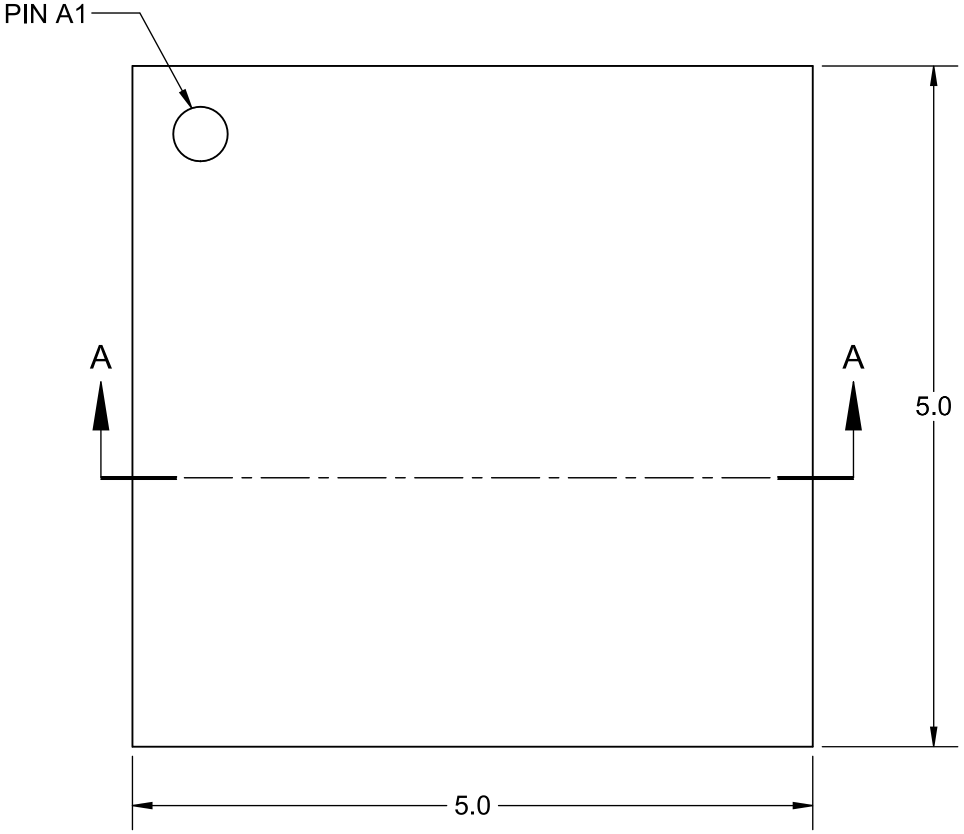
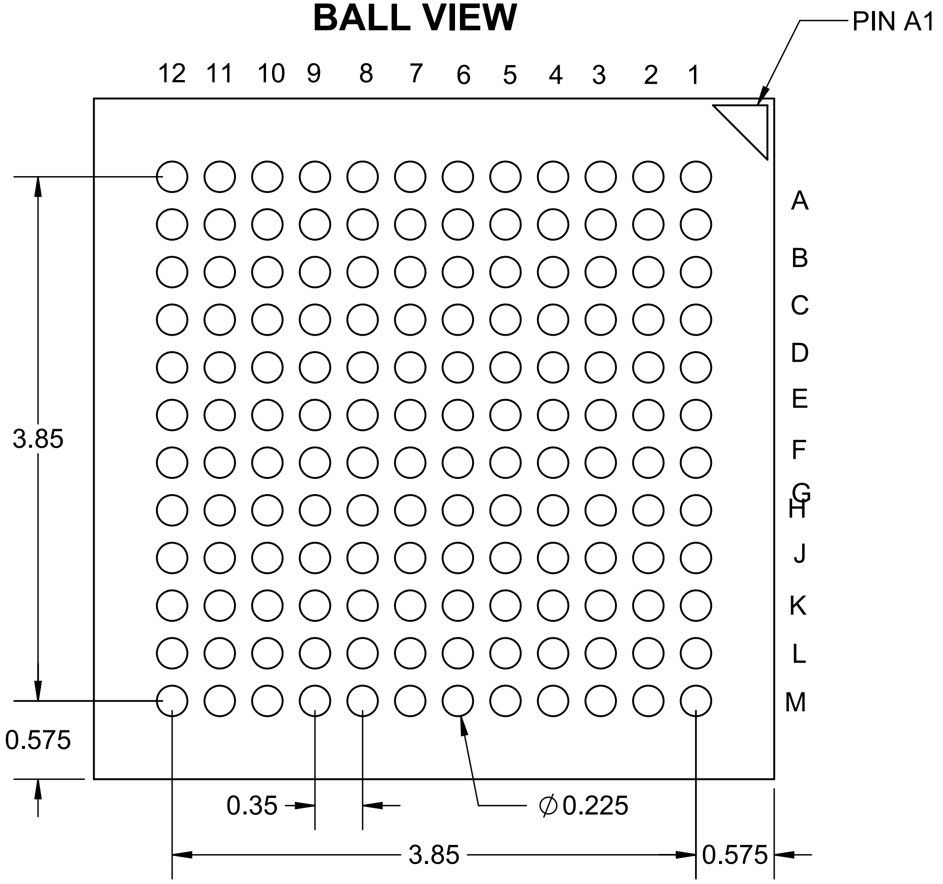
TOP VIEW

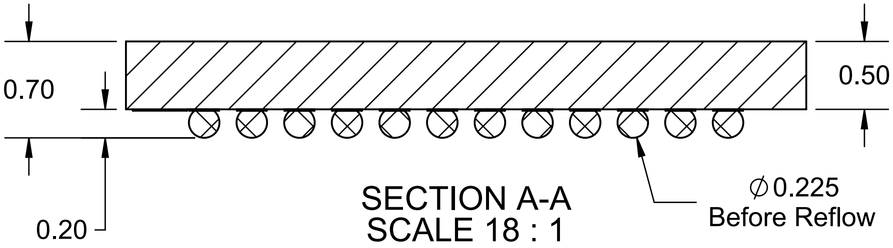


BALL VIEW



Notes: (Unless Otherwise Specified).

1) ALL DIMENSIONS: MM.
2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
3) BALL DIAMETER (BEFORE REFLOW): 0.225mm.
4) SOLDER MASK DEFINED PAD OPENING: 0.20mm (8 MIL).
5) PAD Cu DIAMETER: 0.25mm (10 MIL).
6) SUBSTRATE MATERIAL: BT.
7) DUMMY DIE IS OPTIONAL.
8) ISOLATED PAD PATTERN (SEE PAGE 2).
9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.



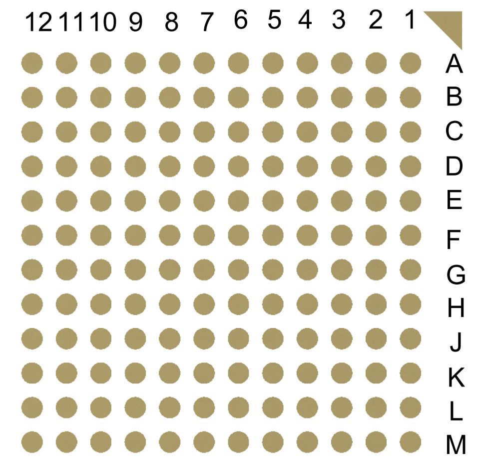
SECTION A-A
SCALE 18 : 1

**PART NUMBER TABLE**

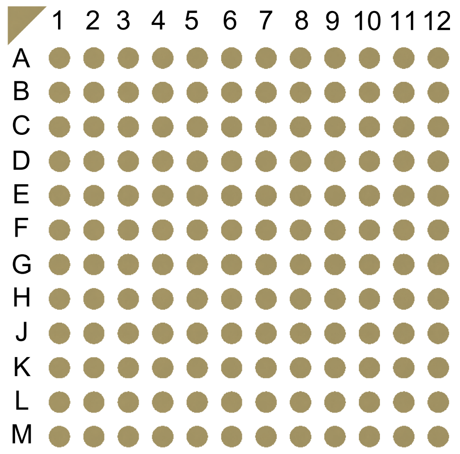
| PART NUMBER | BALL ALLOY | Pb-FREE | RoHS | Si DIE |
|---|---|---|---|---|
| LBGA144T.35C-ISO | Sn96.5/Ag3.0/Cu0.5 | YES | YES | NO |
| LBGA144T.35-ISO | Sn63/Pb37 | NO | NO | NO |

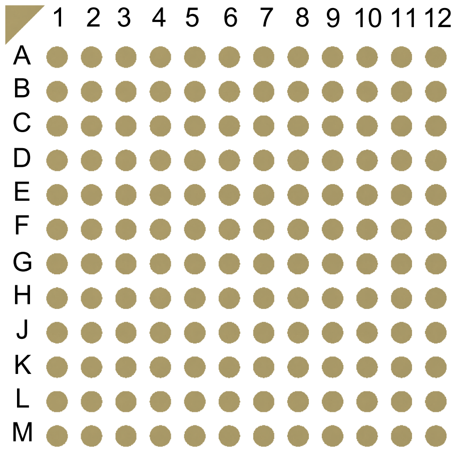
| APPROVALS | | DATE | TopLine® | | | |
|---|---|---|---|---|---|---|
| DRAWN | T.Au | 6/29/2023 | | | | |
| ENG | M. Hart | 6/29/2023 | TITLE | LBGA144T.35C-ISO<br>ISOLATED DUMMY BGA | | |
| MFG | | | | | | |
| QA | | | SCALE<br>40:1 | SIZE<br>A | DRAWING NO.<br>571207 | REV<br>A |
| CUST | | | | | | |
| REVISED | | | DO NOT SCALE DRAWING | | SHEET 1 OF 3 | |

## BALL VIEW

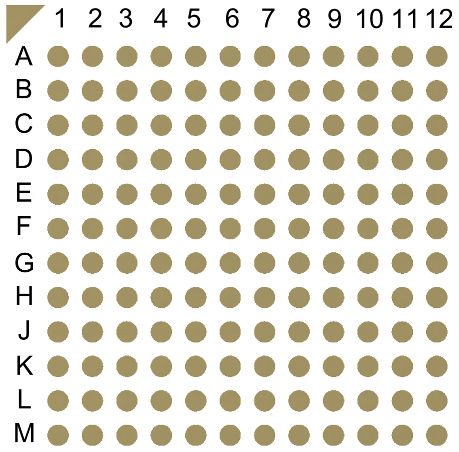


## BOTTOM SIDE
## (TOP X-RAY VIEW)





## TEST VEHICLE BOARD



## AFTER MOUNT

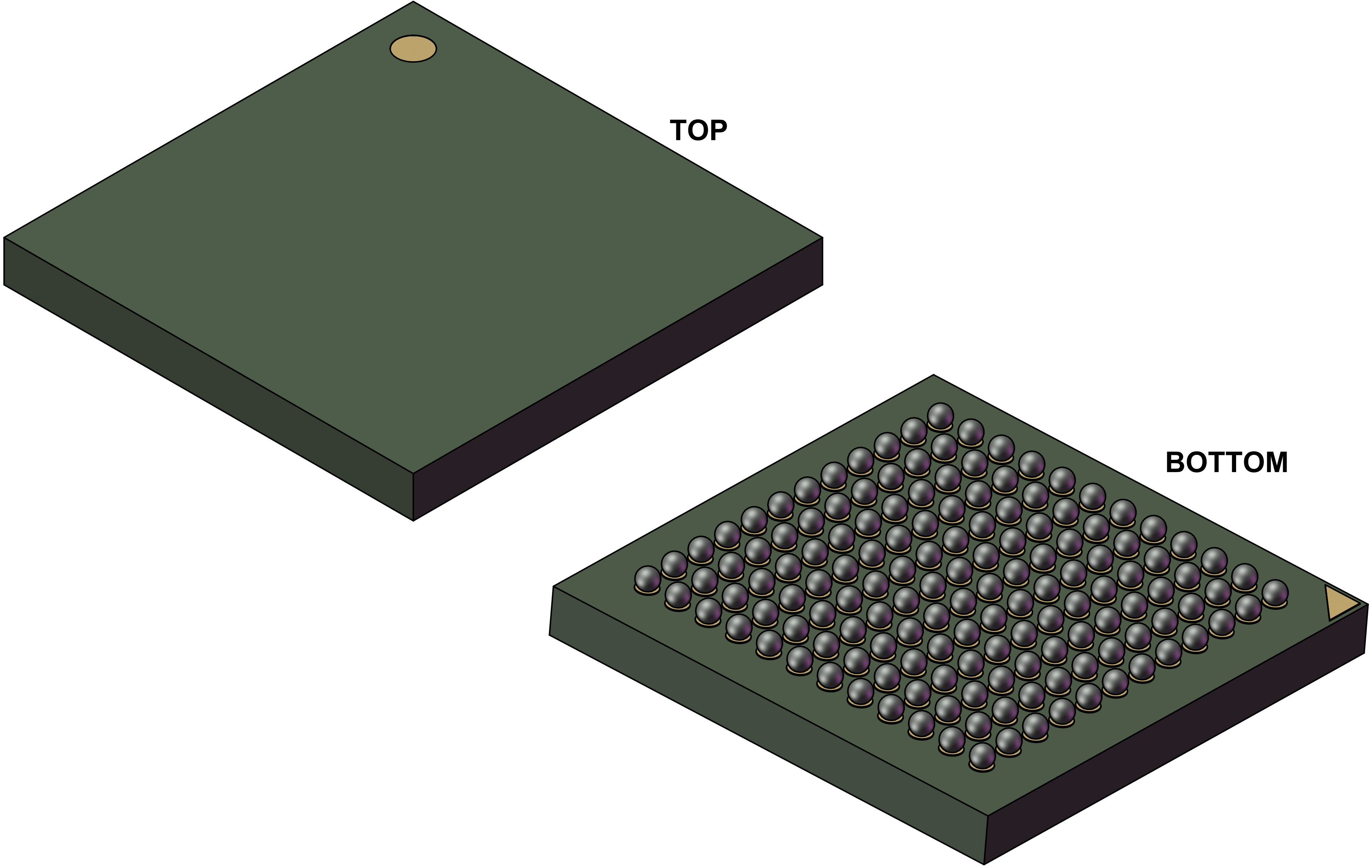
Notes:

1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
2) PCB Cu BALL PAD DIAMETER: ∅0.25mm (10 mil).
3) PCB TRACING LINE WIDTH: 0.127mm (5 mil).
4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.20mm (8 MIL).

**TopLine**®

| | | | |
|---|---|---|---|
| TITLE | LBGA144T.35C-ISO<br>ISOLATED DUMMY BGA | | |
| SCALE<br>25:1 | SIZE<br>A | DRAWING NO.<br>571207 | REV<br>A |
| DO NOT SCALE DRAWING | | SHEET 2 OF 3 | |

## MODEL



**TopLine®**

| | | | |
|---|---|---|---|
| TITLE | LBGA144T.35C-ISO<br>ISOLATED DUMMY BGA | | |
| SCALE<br>40:1 | SIZE<br>A | DRAWING NO.<br>571270 | REV<br>A |
| DO NOT SCALE DRAWING | | SHEET 3 OF 3 | |